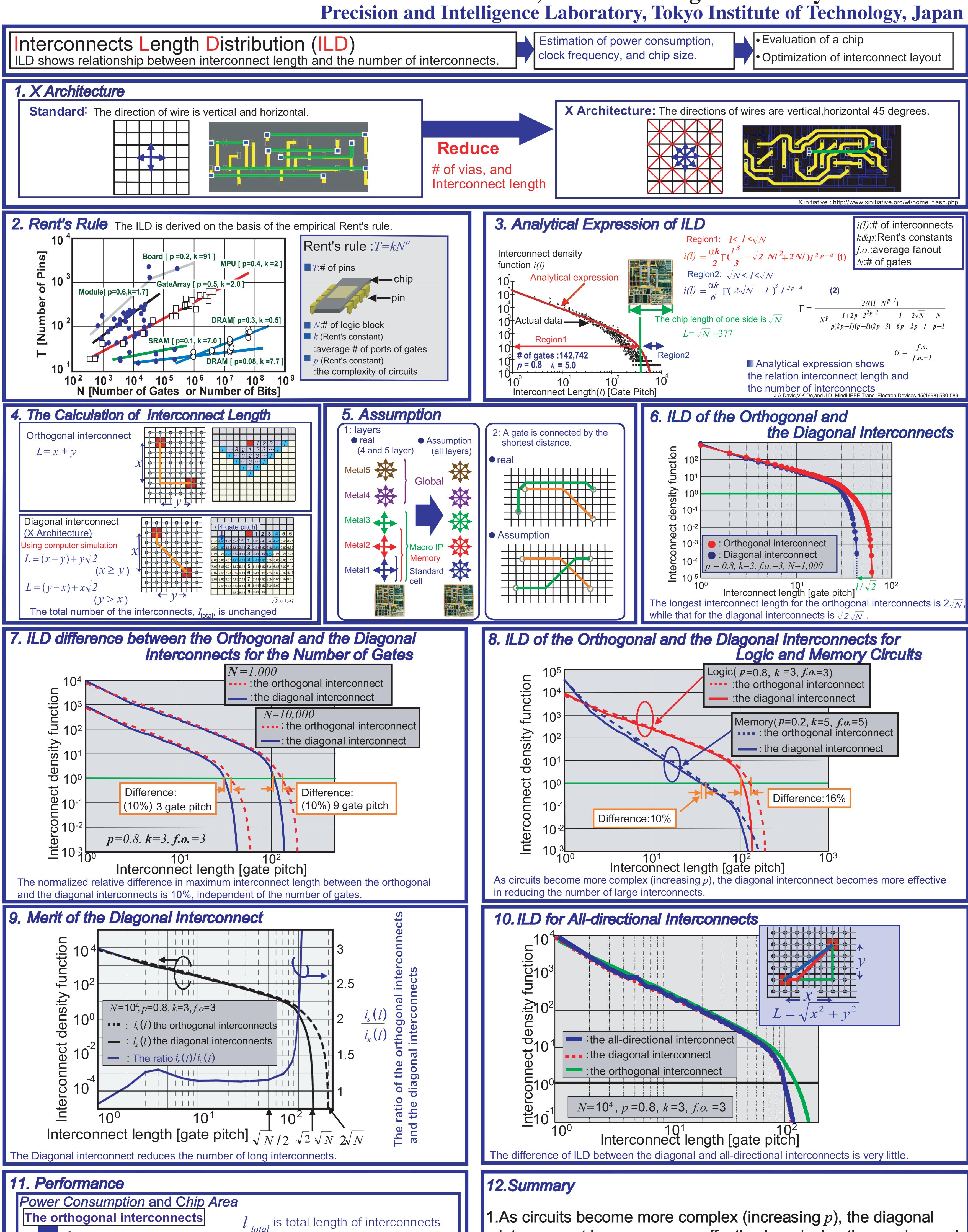
Derivation of Interconnect Length Distribution in X Architecture LSIs

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l total reduces 17%

The diagonal interconnects

The orthogonal interconnects

The diagonal interconnects

lave reduces 18%

Clock frequency reduces 18%

Clock Frequency

Power Consumption and Chip Area reduces 17%

 $P = a \frac{1}{2} V_{dd}^2 f_c C_{unit} l_{total} \quad A_C = p_m l_{total}$

 l_{ma} is average interconnects length

 $T_g = R_{gout} f.o.(0.86c_{int}l_{avg} + 0.86C_{gin})$

H. B. Bakoglu, Circuits, Interconnections, and Packaging for VLSI. Reading, MA: Addison-Wesley, 1990.

 $+ r_{int} l_{avg} (0.37 c_{int} l_{avg} + 0.86 C_{gin})$

- 1.As circuits become more complex (increasing p), the diagonal interconnect becomes more effective in reducing the number and length of interconnects.
- 2.Using the X Architecture instead of the conventional orthogonal interconnects, both the interconnection area and the power consumption of interconnects decrease by 17% and the clock frequency increase by 18%.
- 3.The difference of ILD between the diagonal and all-directional interconnects is very little. The X Architecture is sufficient to reduce the number of long interconnects.